

LNPTM THERMOCOMPTM COMPOUND UF008AS

UF-1008 A

DESCRIPTION

LNP THERMOCOMP UF008AS is a compound based on Polyphthalamide resin, containing Glass Fiber. Added features include; Mold Release.

TYPICAL PROPERTY VALUES

Revision 20191212

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, break, 5 mm/min	234	MPa	ISO 527
Tensile Strain, break, 5 mm/min	2.1	%	ISO 527
Tensile Modulus, 1 mm/min	14500	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	315	MPa	ISO 178
Flexural Modulus, 2 mm/min	12000	MPa	ISO 178
IMPACT			
Izod Impact, unnotched 80*10*4 +23°C	55	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	13	kJ/m ²	ISO 180/1A
THERMAL			
CTE, 23°C to 60°C, flow	2.3E-05	1/°C	ISO 11359-2
CTE, 23°C to 60°C, xflow	5.3E-05	1/°C	ISO 11359-2
PHYSICAL			
Mold Shrinkage, flow	0.14	%	SABIC method
Density	1.53	g/cm ³	ISO 1183
INJECTION MOLDING			
Drying Temperature	120 – 150	°C	
Drying Time	4	hrs	
Maximum Moisture Content	0.15	%	
Melt Temperature	315 – 330	°C	
Front - Zone 3 Temperature	325 – 340	°C	
Middle - Zone 2 Temperature	315 – 325	°C	
Rear - Zone 1 Temperature	310 – 320	°C	
Mold Temperature	140 – 165	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

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